PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5632666

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HIDEYUKI SEKINE	07/05/2019

RECEIVING PARTY DATA

Name:	TAIYO YUDEN CO., LTD.
Street Address:	7-19 KYOBASHI 2-CHOME, CHUO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	104-0031

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16520034

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone:	202-216-9505
Email:	docketing@steinip.com
Correspondent Name:	STEIN IP, LLC
Address Line 1:	1990 M STREET, NW
Address Line 2:	SUITE 610
Address Line 4:	WASHINGTON, D.C. 20036

ATTORNEY DOCKET NUMBER:	0855.1017
NAME OF SUBMITTER:	MICHAEL D. STEIN
SIGNATURE:	/Michael D. Stein/
DATE SIGNED:	07/23/2019

Total Attachments: 1

source=10280US_Combined Declaration-Assignment#page1.tif

Form (Rev. 4/2013) UNITED STATES Docket No.:

COMBINED DECLARATION/ASSIGNMENT FOR UTILITY/DESIGN PATENT APPLICATION

OATH OR DECLARATION

As a below named inventor, I hereby declare that:

This combined declaration and assignment is directed to the application entitled:

HIGH-PASS FILTER AND MULTIPLEXER

the specification of which is attached hereto, or was filed on ____________ as United States Application Number (or PCT International Application Number) ____________ and was amended on ____________ (if applicable).

Any registered attorney of STEIN IP, LLC, 1990 M St., N.W., Suite 610, Washington, D.C. 20036 (202-216-9505), USPTO Customer Number 49,455, is hereby authorized to insert the specified data into the above paragraph, when known.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

IN CONSIDERATION of good and valuable consideration paid to me, an undersigned inventor, by

Taiyo Yuden Co., Ltd.
7-19 Kyobashi 2-chome, Chuo-ku, Tokyo, 104-0031, Japan

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, I hereby sell, assign and transfer to ASSIGNEE the entire and exclusive right, title and interest to the above-identified application and the claimed invention therein, and any continuation, division, renewal, substitute, reissue or reexamination application based thereon (collectively, hereinafter, "said application(s)"), and all Letters Patent of the United States granted on said application(s), for the full term or terms for which the said Letters Patent may be granted and including any extensions thereof (collectively, hereinafter, "said Letters Patent").

I agree, when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent, in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

I covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

IN WITNESS WHEREOF, I have affixed my signature on the date beneath.

Full name of sole/first inventor Hideyuki SEKINE

Inventor's Signature Hideyuki Sekine Date Executed July. 5. 2019

Inventor's Mailing Address c/o TAIYO YUDEN Mobile Technology Co., Ltd., 6-16-3, Shinmachi, Ome-shi, Tokyo 198-0024, Japan
Inventor's Residence Tokyo, JAPAN